Failure Analysis Student – Amazon

DESCRIPTION

· Preparation and inspection of metallographic cross-sections of solder joints and electronic components for routine monitoring and failure analysis.
· Preparation of samples for failure analysis of IC’s
· Take part in the development of techniques for sample preparation
· You will have an opportunity to be exposed to state-of-the-art techniques and tools for debug and failure analysis, like FIB, Electron microscopy and photonic methods for debug and fault isolation.

BASIC QUALIFICATIONS

· Student for B.Sc in Materials/chemical engineering or higher. Or a student for M.Sc in Chemistry. At least one year of remaining studies.
· Available at least 20 hours a week. Working in shifts is also possible.
· Personal skills:
  - Organized
  - Highly motivated and Diligent
  - Hands-on person
  - Good teamwork and good communication skills, but yet have the ability to handle tasks independently
Proficiency in written and spoken English

PREFERRED QUALIFICATIONS

· Experience in preparing and inspecting metallographic cross-sections
· Experience with SEM and/or TEM
· Experience with FIB
· Hands-on experience with acids
· Relevant courses in VLSI processing, electronics packaging and assembly, metallurgy, electron microscopy.

https://www.amazon.jobs/en/jobs/758582/failure-analysis-student